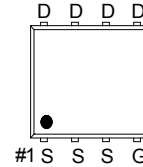
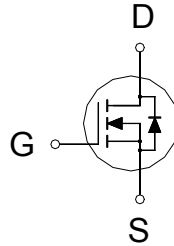


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D^3
20V	5m Ω	47A



G : GATE
D : DRAIN
S : SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	20	V
Gate-Source Voltage		V_{GS}	± 8	V
Continuous Drain Current ³	$T_C = 25\text{ }^\circ\text{C}$	I_D	47	A
	$T_C = 100\text{ }^\circ\text{C}$		30	
	$T_A = 25\text{ }^\circ\text{C}$		15	
	$T_A = 70\text{ }^\circ\text{C}$		12	
Pulsed Drain Current ¹		I_{DM}	70	
Avalanche Current		I_{AS}	38.6	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	74.6	mJ
Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	P_D	19	W
	$T_C = 100\text{ }^\circ\text{C}$		7	
	$T_A = 25\text{ }^\circ\text{C}$		2	
	$T_A = 70\text{ }^\circ\text{C}$		1.3	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	$R_{\theta JA}$		60	$^\circ\text{C} / \text{W}$
Junction-to-Case	$R_{\theta JC}$		6.5	

¹Pulse width limited by maximum junction temperature.

²The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25\text{ }^\circ\text{C}$.

³Package limitation current is 22A

ELECTRICAL CHARACTERISTICS ($T_j = 25\text{ }^\circ\text{C}$, Unless Otherwise Noted)

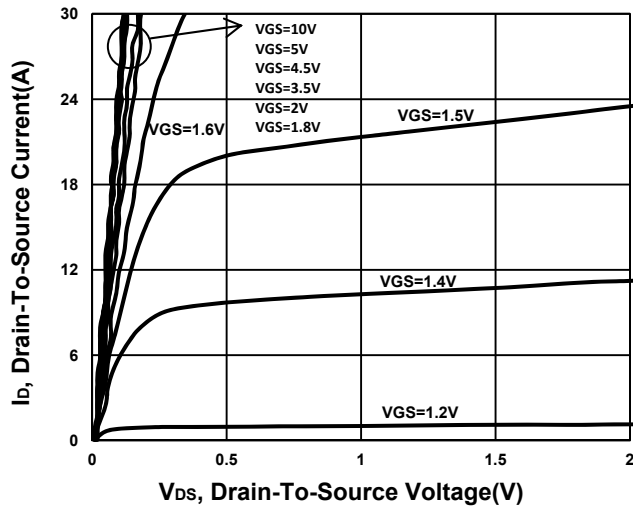
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	20			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.4	0.7	0.9	

Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 8V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 16V, V_{GS} = 0V$			1	μA
		$V_{DS} = 10V, V_{GS} = 0V, T_J = 55\text{ }^{\circ}C$			10	
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 4.5V, I_D = 5A$		4.1	5	m Ω
		$V_{GS} = 2.5V, I_D = 5A$		4.7	5.7	
		$V_{GS} = 1.8V, I_D = 5A$		6	8.2	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 5A$		70		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 10V, f = 1MHz$		4407		pF
Output Capacitance	C_{oss}			469		
Reverse Transfer Capacitance	C_{rss}			381		
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		0.7		Ω
Total Gate Charge ²	Q_g	$V_{GS}=4.5V, V_{DS} = 10V, I_D = 5A$		49		nC
Gate-Source Charge ²	Q_{gs}			6		
Gate-Drain Charge ²	Q_{gd}			13		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DD} = 4.5V$ $I_D \cong 5A, V_{GEN} = 10V, R_G = 6\Omega$		20		nS
Rise Time ²	t_r			25		
Turn-Off Delay Time ²	$t_{d(off)}$			180		
Fall Time ²	t_f			85		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25\text{ }^{\circ}C$)						
Continuous Current ³	I_S				14	A
Forward Voltage ¹	V_{SD}	$I_F = 5A, V_{GS} = 0V$			1.3	V
Reverse Recovery Time	t_{rr}	$I_F = 5A, di_F/dt = 100A / \mu S$		24		nS
Reverse Recovery Charge	Q_{rr}			12		nC

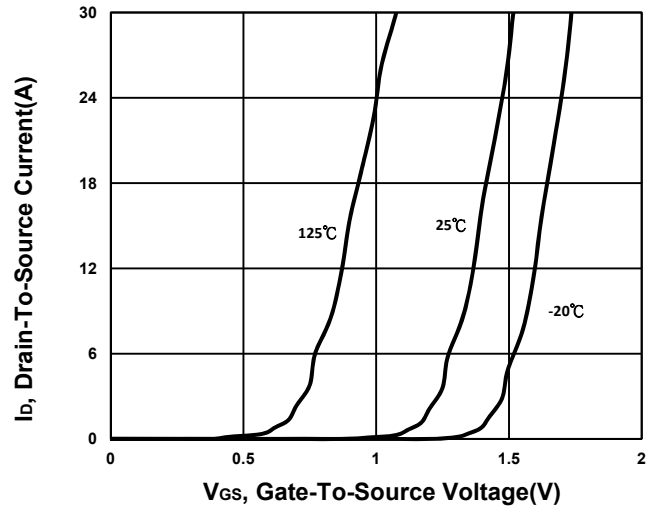
¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

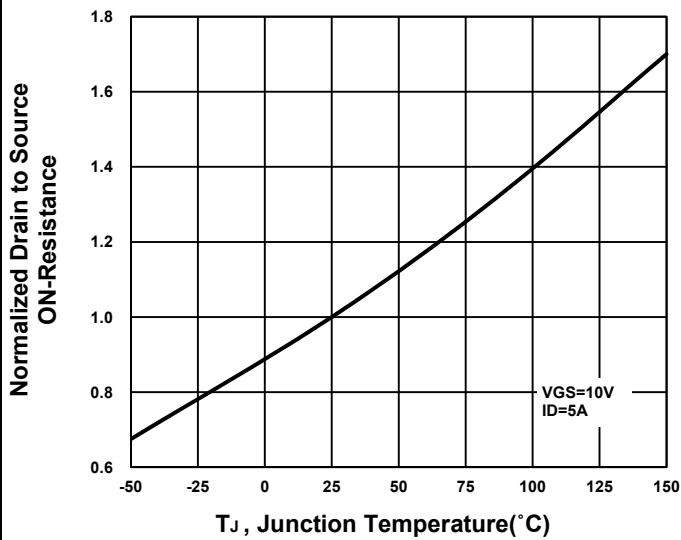
Output Characteristics



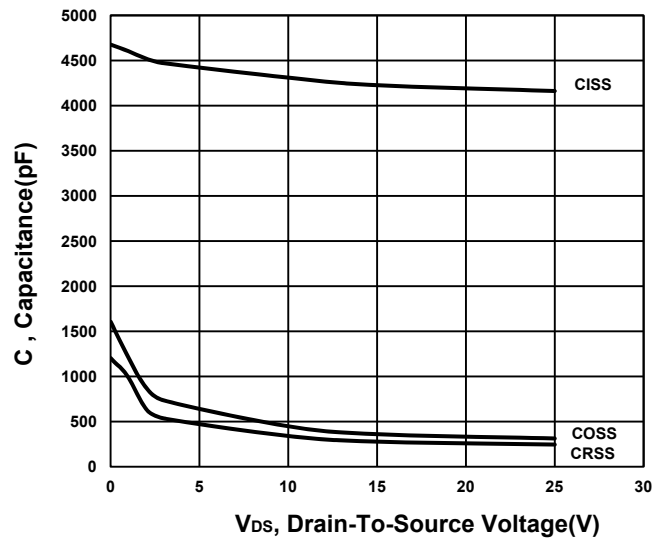
Transfer Characteristics



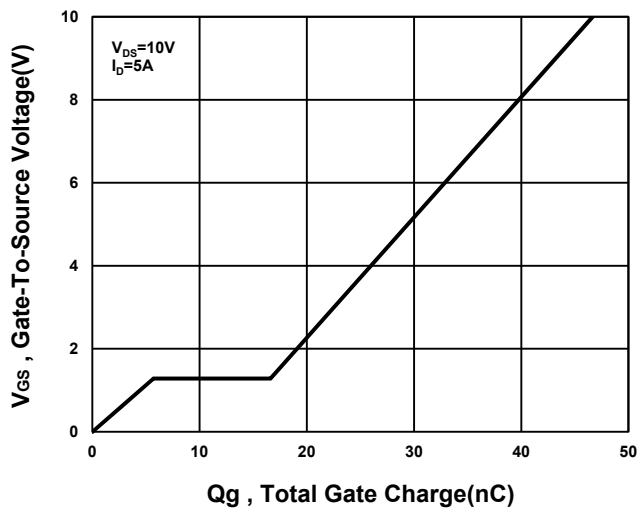
On-Resistance VS Temperature



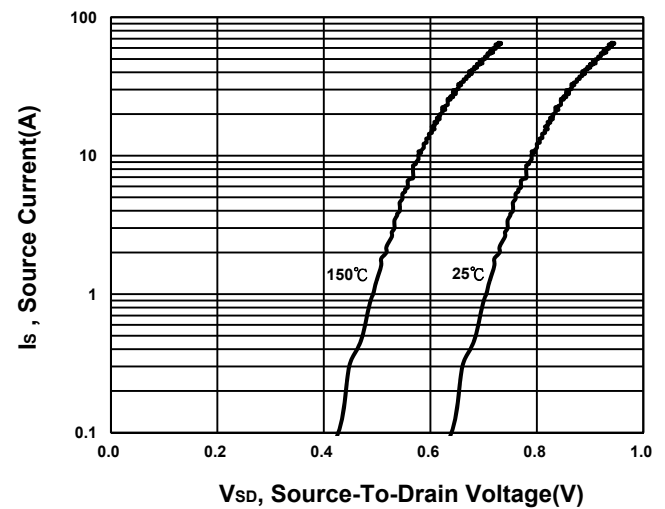
Capacitance Characteristic



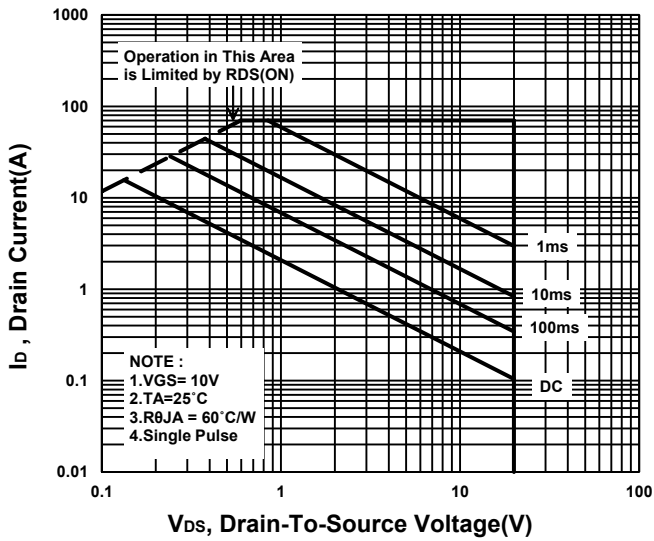
Gate charge Characteristics



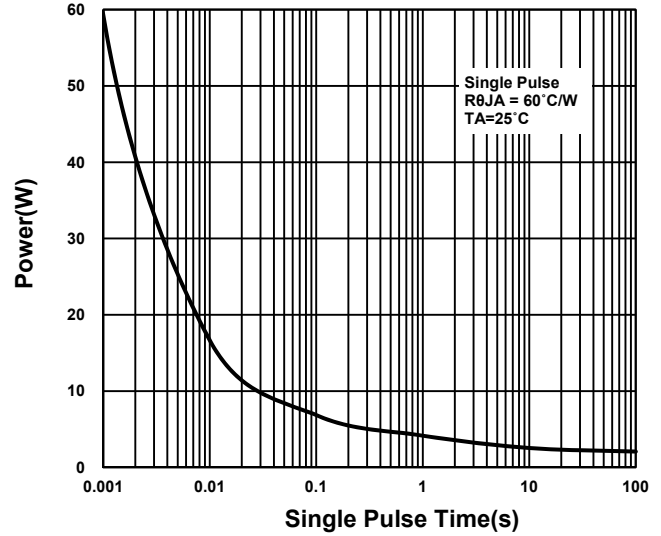
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

